# FP1008R1 and FP1008R2

# High frequency, high current power inductors



#### **Product description**

- · High current carrying capacity
- · Low core loss
- · Controlled DCR for sensing circuits
- Inductance range from 120nH to 300nH
- Current range from 38 to 112 amps
- 10.8 x 8.0 mm footprint surface mount package in an 8.0 mm height
- Ferrite core material
- · Halogen free, lead free, RoHS compliant

#### **Applications**

- Servers
- Multi-phase and Vcore regulators
- Voltage Regulator Modules (VRMs)
- Desktop VRMs and EVRDs
- · Data networking and storage systems
- · Graphics cards and battery power systems
- · Point-of-Load modules
- · DCR Sensing circuits

#### **Environmental data**

- Storage temperature range (Component): -40°C to +125 °C
- Operating temperature range: -40°C to +125°C (ambient + self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant









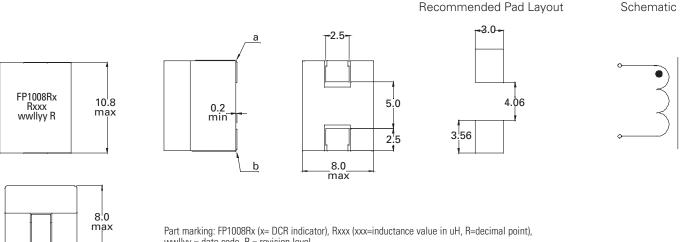
#### **Product specifications**

Part Number <sup>9</sup>	OCL <sup>1</sup> (nH)±10%	FLL <sup>2</sup> (nH) minimum	l <sub>rms</sub> ³ (amps)	I <sub>sat</sub> 1 <sup>4</sup> (amps)	l <sub>sat</sub> 2 <sup>5</sup> (amps)	I <sub>sat</sub> 3 <sup>6</sup> (amps)	DCR (mΩ) ±5% @ 20°C	K-factor <sup>7</sup>
R1 version								
FP1008R1-R120-R	120	86	79	112	92	84	0.17	342
FP1008R1-R150-R	150	108	79	90	72	67	0.17	342
FP1008R1-R180-R	180	130	79	74	60	54	0.17	342
FP1008R1-R220-R	220	158	79	56	44	42	0.17	342
FP1008R1-R270-R	270	194	79	44	34	32	0.17	342
FP1008R1-R300-R	300	216	79	38	30	28	0.17	342
R2 version								
FP1008R2-R120-R	120	86	74	112	92	84	0.18	342
FP1008R2-R150-R	150	108	74	90	72	67	0.18	342
FP1008R2-R180-R	180	130	74	74	60	54	0.18	342
FP1008R2-R220-R	220	158	74	56	44	42	0.18	342
FP1008R2-R270-R	270	194	74	44	34	32	0.18	342
FP1008R2-R300-R	300	216	74	38	30	28	0.18	342

- 1. Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.1V<sub>ms</sub>, 0.0Adc, +25°C
- 2. Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V<sub>rms</sub>, I<sub>sat</sub>1, +25°C
- 3. I<sub>ms</sub>: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.
- 4. I<sub>sat</sub>1: Peak current for approximately 20% rolloff @ +25°C
- 5. I<sub>sat</sub>2: Peak current for approximately 20% rolloff @ +100°C
- 6. I<sub>sat</sub> 3: Peak current for approximately 20% rolloff @ +125°C

- K-factor: Used to determine B<sub>pp</sub> for core loss (see graph).
   B<sub>pp</sub> = K \* L \* ΔI \* 10<sup>-3</sup>. B<sub>pp</sub> (Gauss), K: (K-factor from table),
   L: (Inductance in nH), ΔI (Peak-to-peak ripple current in Amps).
- 8. Part Number Definition: FP1008Rx-Rxxx-R FP1008 R= Product code and size
  - x = DCR indicator
  - Rxxx = Inductance value in  $\mu H$ , R = decimal point
  - R suffix = RoHS compliant

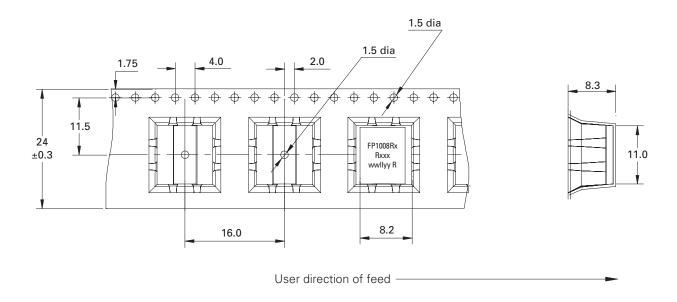
#### Dimensions (mm)



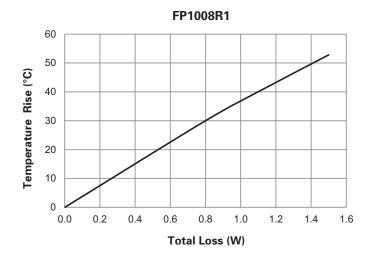
Part marking: PP1008fx (x= DCR indicator), Hxxx (xxx=inductance valid willyy = date code, R = revision level Tolerances are ±0.15 millimeters unless stated otherwise PCB tolerances are ±0.1 millimeters unless stated otherwise All soldering surfaces to be coplanar within 0.1 millimeter DCR measured from point "a" to point "b" Do not route traces or vias underneath the inductor

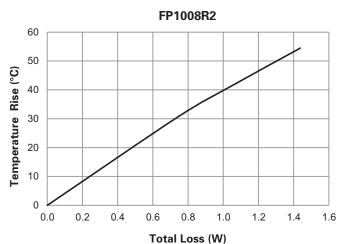
# Packaging information (mm)

Supplied in tape and reel packaging, 500 parts per 13" diameter reel.

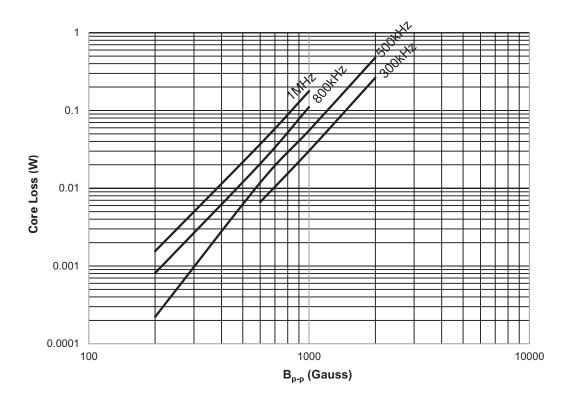


# Temperature rise vs. total loss

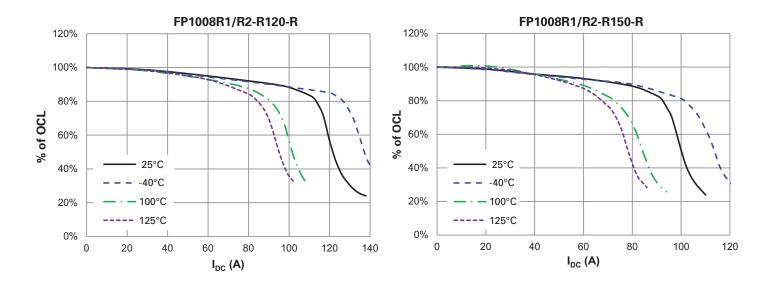




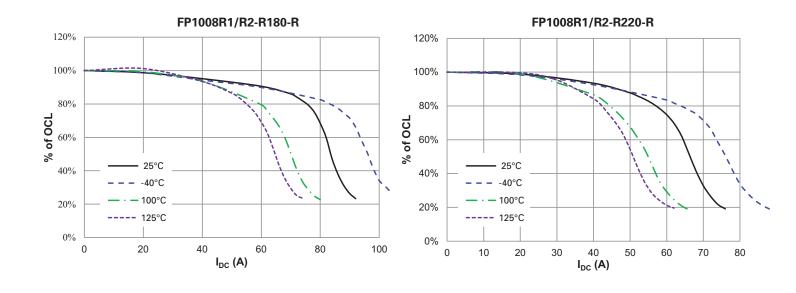
# Core loss vs. Bp-p

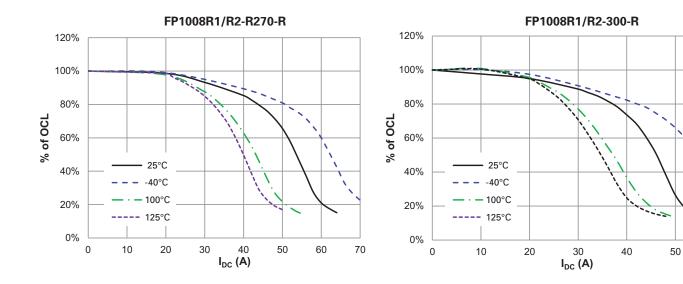


# **Inductance characteristics**



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## Solder reflow profile

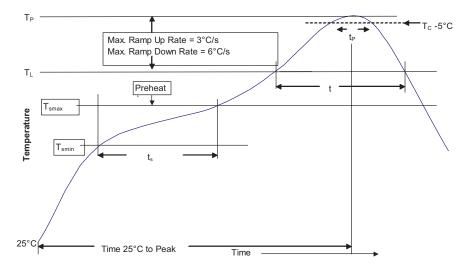


Table 1 - Standard SnPb Solder (T<sub>C</sub>)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T<sub>C</sub>)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

#### Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak • Temperature min. (T <sub>smin</sub> )	100°C	150°C	
• Temperature max. (T <sub>smax</sub> )	150°C	200°C	
• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds	60-120 Seconds	
Average ramp up rate $T_{smax}$ to $T_p$	3°C/ Second Max.	3°C/ Second Max.	
Liquidous temperature (TL) Time at liquidous (tL)	183°C 60-150 Seconds	217°C 60-150 Seconds	
Peak package body temperature (Tp)*	Table 1	Table 2	
Time (t <sub>p</sub> )** within 5 °C of the specified classification temperature (T <sub>c</sub> )	20 Seconds**	30 Seconds**	
Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> )	6°C/ Second Max.	6°C/ Second Max.	
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.	

 $<sup>^{*}</sup>$  Tolerance for peak profile temperature (T $_{\rm p}$ ) is defined as a supplier minimum and a user maximum.

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<sup>\*\*</sup> Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.